

### General Description

The PST20G04 is the highest performance trench N-ch and P-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the synchronous buck converter applications.

The PST20G04 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

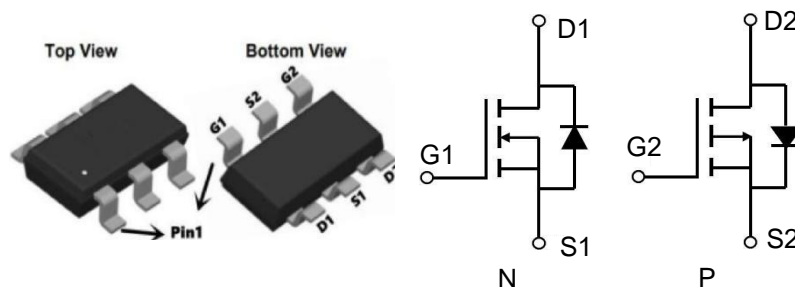
### Product Summary

BVDSS	R <sub>DS(on)</sub>	ID
20V	22mΩ	5A
-20V	55 mΩ	- 3.6A

### Applications

- Power management in half bridge and inverters
- DC-DC Converter
- Load Switch

### SOT23-6L Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V <sub>DS</sub>	Drain-Source Voltage	20	-20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	±12	V
I <sub>D@T<sub>C</sub>=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5	-3.6	A
I <sub>D@T<sub>C</sub>=100°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	4	-2.5	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	-12	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	72	59	mJ
I <sub>AS</sub>	Avalanche Current	21	-19	A
P <sub>D@T<sub>C</sub>=25°C</sub>	Total Power Dissipation <sup>4</sup>	2.5	2.08	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	50	°C/W

### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.4	0.7	1	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note2</small>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	-	22	27	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =3A	-	29	44	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1.0MHz	-	358	-	pF
C <sub>oss</sub>	Output Capacitance		-	69.3	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	58.5	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =10V, I <sub>D</sub> =2A, V <sub>GS</sub> =4.5V	-	5.6	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	0.8	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	1	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =10V, I <sub>D</sub> =4A, R <sub>GEN</sub> =3Ω, V <sub>GS</sub> =4.5V	-	5	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	30	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	48	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	36	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	5	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	16	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =4A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V,	-	-	-1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±12V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.5	-0.7	-1.0	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note2</small>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3A	-	55	70	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -2A	-	70	100	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -10V, V <sub>GS</sub> =0V, f=1.0MHz	-	503	-	pF
C <sub>oss</sub>	Output Capacitance		-	67	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	58	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -10V, I <sub>D</sub> = -2A, V <sub>GS</sub> = -4.5V	-	4.1	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	0.8	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	1.1	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> = -10V, I <sub>D</sub> = -3A, R <sub>G</sub> =1Ω, V <sub>GEN</sub> = -4.5V, R <sub>L</sub> =1.2Ω	-	11	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	52	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	16	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	10	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-3	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-12	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = -3A	-	-	-1.2	V

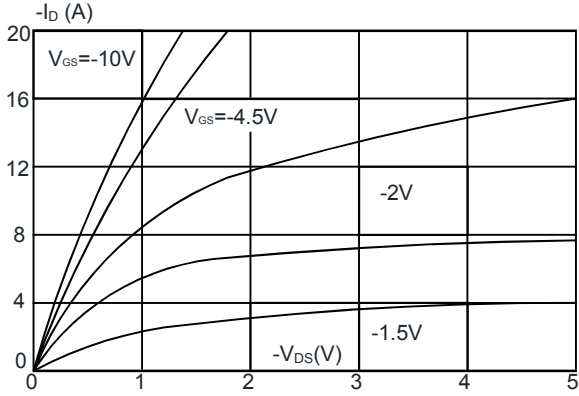
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

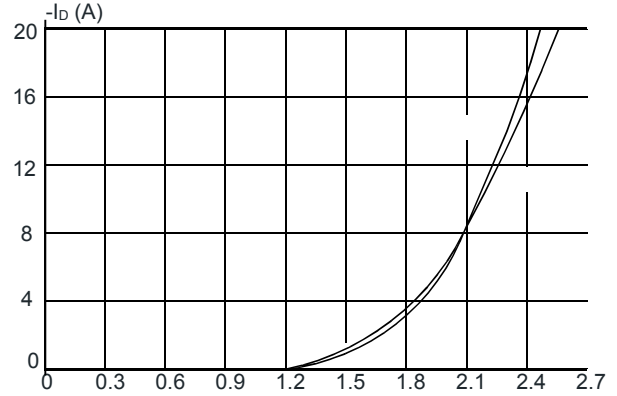
### Typical Performance Characteristics

#### P-Channel Typical Characteristics

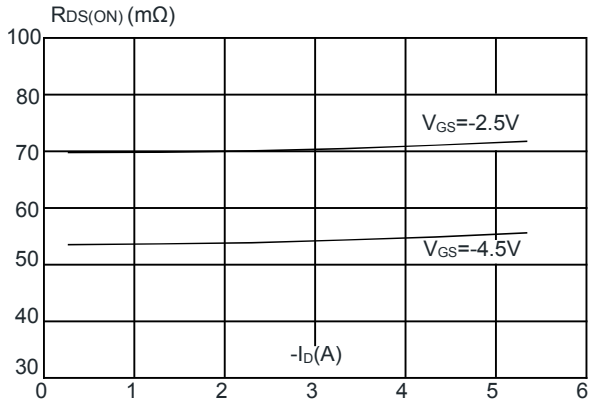
**Figure 1:** Output Characteristics



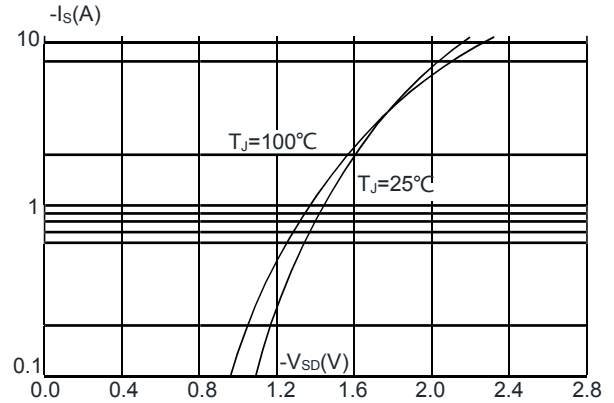
**Figure 2:** Typical Transfer Characteristics



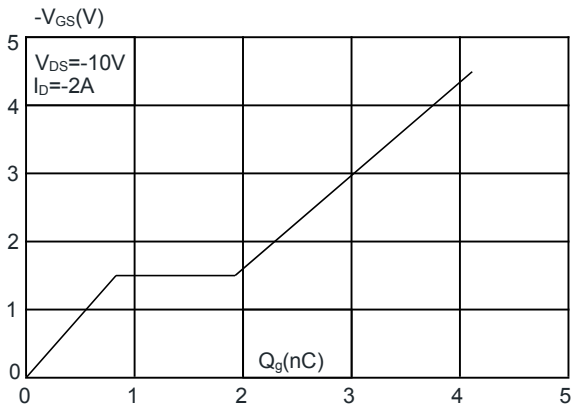
**Figure 3:** On-resistance vs. Drain Current



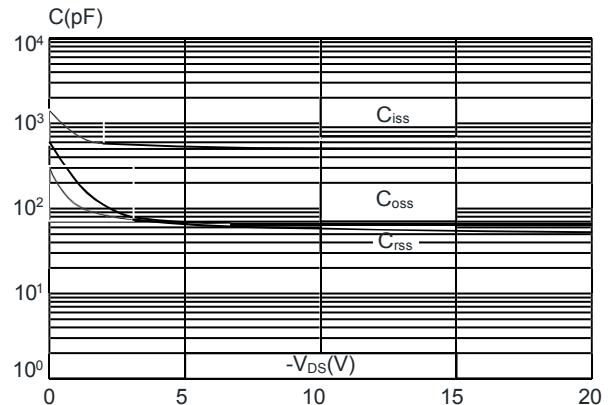
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

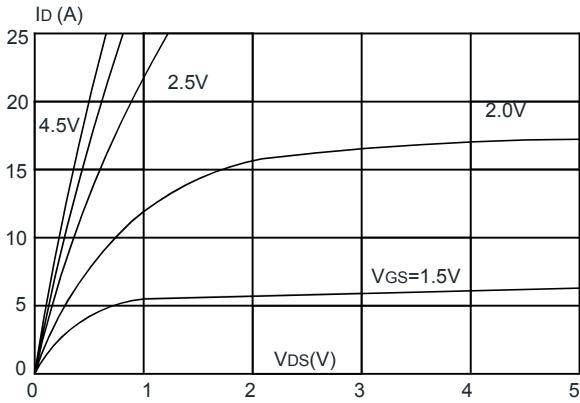


**Figure 6:** Capacitance Characteristics

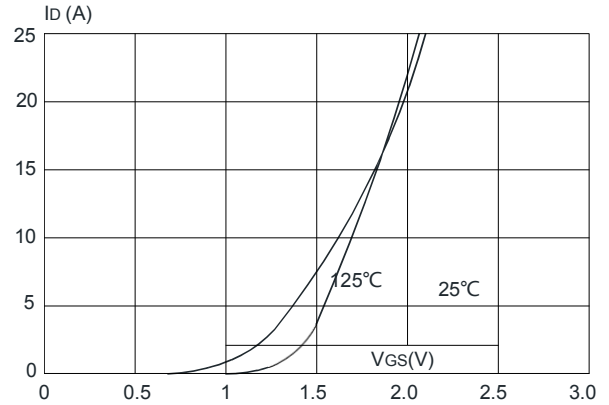


### N-Channel Typical Characteristics

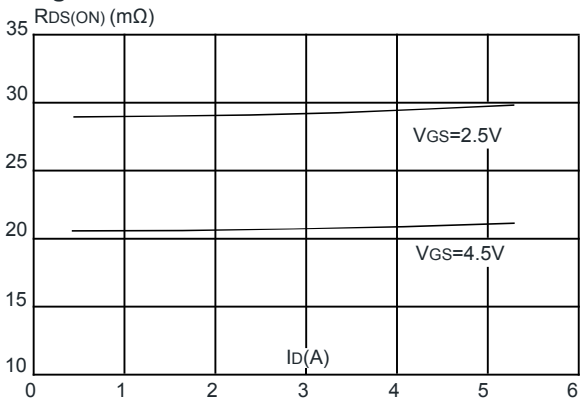
**Figure 1:** Output Characteristics



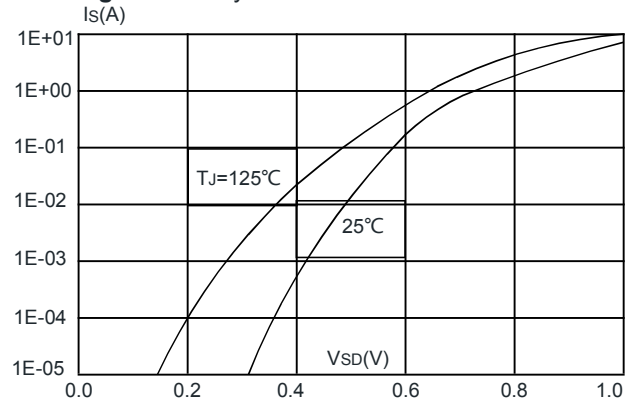
**Figure 2:** Typical Transfer Characteristics



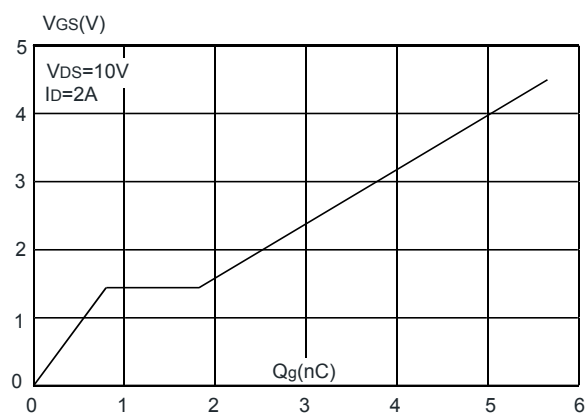
**Figure 3:** On-resistance vs. Drain Current



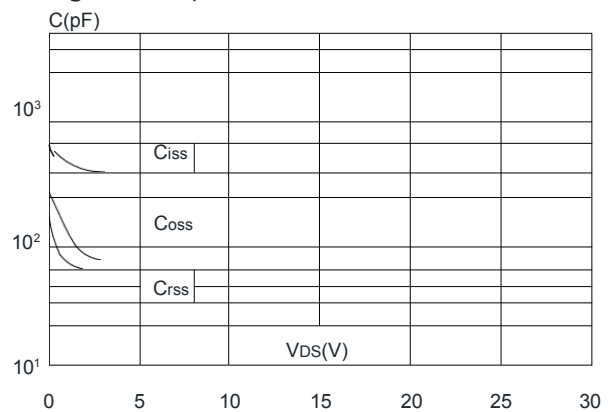
**Figure 4:** Body Diode Characteristics



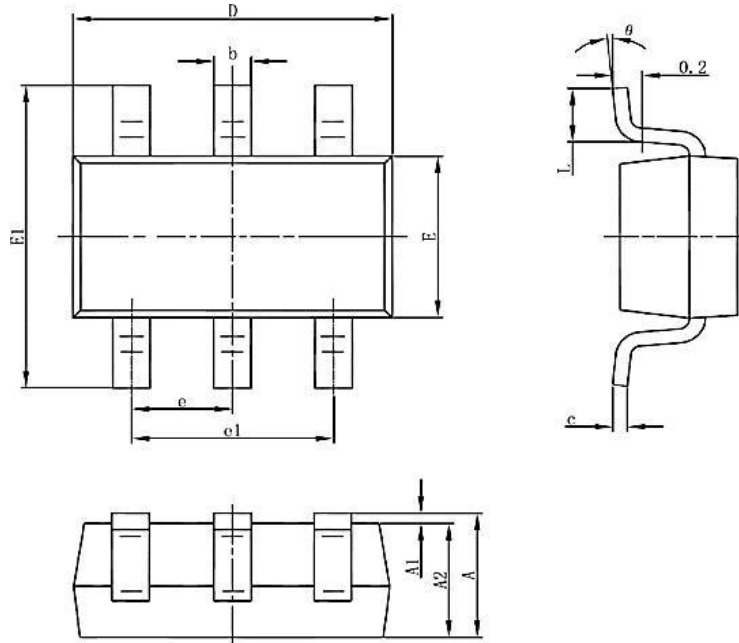
**Figure 5:** Gate Charge Characteristics



**Figure 6:** Capacitance Characteristics



Package Mechanical Data-SOT23-6-Double



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
C	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950 (BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0	8	0	8